# **Preliminary Specifications**

Drawing No.	USY1N-H1-18600-00
Issued Date.	Oct,1,2018

# Messrs: Digikey

Note: Part Number will be revised in case of specification change.

Product Type	Quartz Crystal	
Series	CX2016DB	
Frequency	16000kHz	
Customer Part Number		
Customer Specification Number		
KYOCERA Part Number	CX2016DB16000D0GLJCC	
Remarks Pb-Free, RoHS Compliant, MSL 1		

#### **Customer Approval**

Approval Signature	Approved Date	
	Department	
	Person in charge	
	_	

#### Seller

## **KYOCERA** Corporation

Corporate Electronic Components Group Electronic Components Sales Division 6 Takeda Tobadono-cho, Fushimi-ku, Kyoto 612-8501 Japan TE: 075-604-3500 FAX: 075-604-3501

#### Manufacturer

Corporate Electronic Components Group Crystal Components Division Shiga Yohkaichi Plant 1166-6 Hebimizo-cho, Higashiomi, Shiga 527-8555 Japan TEL: 0748-22-1550 FAX: 0748-22-1590

Design Department	Quality Assurance	Approved by	Checked by	Issued by
KYOCERA Corporation	K.Shimizu	T.Fujii	A.Muraoka	R.Yoshida
Crystal Units Design Engineering Section				Y.Nozaki
Crystal Product Division				

Drawing No. USY1N-H1-18600-00

## **Revision History**

Rev.No.	Description of revision	Date	Approved by	Checked by	Issued by
00	First Edition	Oct,1,2018	T.Fujii	A.Muraoka	R.Yoshida Y.Nozaki

## **1. APPLICATION**

The purpose of this document is applied to CX2016DB quartz crystal.

## 2. KYOCERA PART NUMBER

CX2016DB16000D0GLJCC

## **3. RATINGS**

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature range	Topr	-30~+85	deg. C	
Storage Temperature range	Tstg	-40~+85	deg. C	

#### 4. CHARACTERISTICS 4-1 ELECTRICAL CHARACTERISTICS

Items		Electrical Specification			Test Condition	Remarks	
	SYMB.	Min	Тур.	Max	Unit		
Mode of Vibration		Fi	undamer	ntal			
Nominal Frequency	F0		16		MHz		
Nominal Temperature	T <sub>NOM</sub>		+25	<	°C		
Load Capacitance	CL		8.0		pF		
Frequency Tolerance	df/F	-15.0		+15.0	/	+25±3°C	
Frequency Temperature Characteristics	df/F	-15.0		+15.0	PPM	-30 to +85°C	
Frequency Aging Rate		-1.0		+1.0		1 <sup>st</sup> Year	+25±3°C
Equivalent Series Resistance	ESR			200	Ω		
Drive Level	Pd	0.01		100	μW		
Insulation Resistance	IR	500			MΩ	100V(DC)	

#### **Measurement Condition**

Frequency measurement

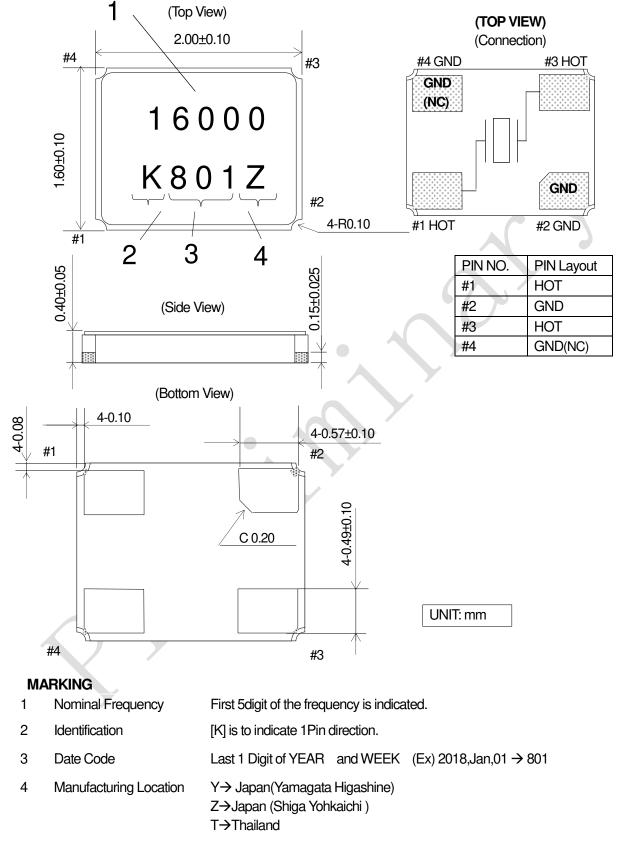
Measuring instrument

: IEC PI-Network Test Fixture IEC 60444-8 STD (Pi circuit 41901A)

Equivalent series resistance (ESR) measurement

Measuring instrument Load Capacitance

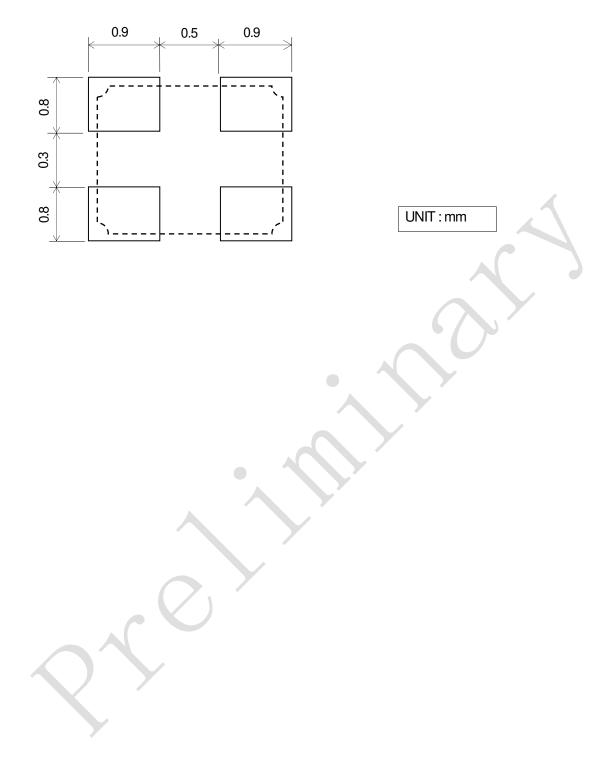
: IEC PI-Network Test Fixture : Series



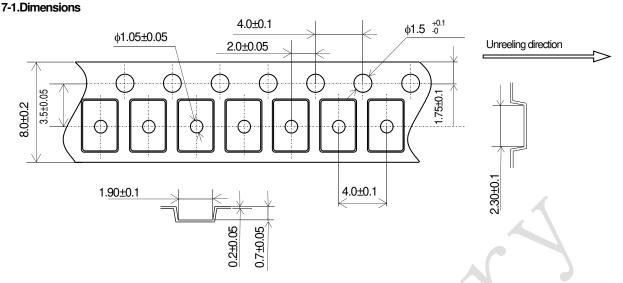
## 5. APPEARANCES, PHYSICAL DIMENSION OUTLINE DIMENSION (not to scale)

#### \*The font of marking is for reference only.

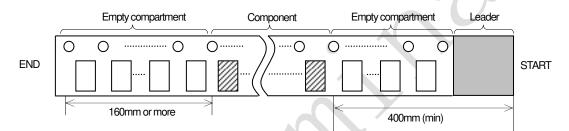
## 6. RECOMMENDED LAND PATTERN (not to scale)



## 7. TAPING & REEL



#### 7-2.Leader and Carrier tape



7-3.Direction (Orientation shall be checked from the top cover tape side)

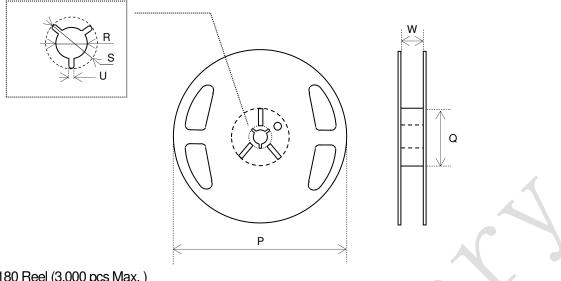


#### 7-4.Specification

- 1. Material of the carrier tape is either polystyrene or A-PET (ESD).
- 2. Material of the cover tape is polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. Tensile strength of carrier tape: 10N or more.
- 5. The R of the corner of each cavity is 0.2RMAX.
- 6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
- 7. The orientation shall be checked from the top cover tape side as shown in 7-3.
- 8. Peeling force of cover tape: 0.1 to 1.0N.
- 9. The component will fall out naturally when cover tape is removed and set upside down.

Cover tape 165°~180 Carrier tape -----1.1

#### 7-5.Reel Specification



## 6180 Reel (3,000 pcs Max. )

Symbol	Р	Q	R
Dimension	φ <b>180 +0/-3</b>	φ <b>60 +1/-</b> 0	φ13±0.2
Symbol	S	U	W
Dimension	φ21±0.8	2.0±0.5	9±1
			(Unit: mm)

#### 6330 Reel (15,000 pcs Max.)

Symbol	Р	Q	R
Dimension	φ330±2.0	φ100±1.0	φ13±0.2
Symbol	S	U	W
Dimension	φ21±0.8	2.0±0.5	9.4±1.0
	*		(1.1.2)

(Unit: mm)

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## 8. Enviromental requirements

After conducting the following tests, component needs to meet below conditions. Frequency: Fluctuation within +/-10 x  $10^{-6}$  CI: Fluctuation within +/-20% or 5 $\Omega$  whichever is larger

8.1	Resistance to Shock	Test condition			
		3 times natural dr	op from 100c	cm onto hard wooden board	l.
8.2	Resistance to Vibration	Test condition			
		frequency		: 10 - 55 - 10 Hz	
		Amplitude		: 1.5mm	
		Cycle time	i.	: 15 minutes	$\sim$
		Direction		: X,Y,Z (3direction),2h each.	3
8.3	Resistance to Heat	Test condition			
		The quartz of	crystal unit sh	nall be stored at a	
		temperature	e of +85±2°C	for 500h and subjected to	
		room tempe	erature for 1h	before measurement.	
8.4	Resistance to Cold	Test condition			
		The quartz of	crystal unit sh	nall be stored at a	
		temperature	e of -40±2°C	for 500h and subjected to	
		room tempe	erature for 1h	before measurement.	
0 5	Thermal Shock	Test soudition			
8.5	Thermal Shock	Test condition		hell he cubicated to 500 too	
			•	hall be subjected to 500 ten	•
		-		elow,Then it shall be subjec	ted
			•	r 1h before mesurement.	
		Cycle		(30min.)→+25±2°C(5min.)	
		-	→ +85±2°C(3	80min.)→ +25±2°C(5min.)	
1	$\mathbf{\nabla}$				

8.6	Resistance to Moisture	Test condition
		The quartz crystal unit shall be stored at a
		temperature of +60±2°C with relative humidity of
		90% to 95% for 240 h. Then it shall be subjected
		to room temperature for 1h before measurement.

8.7 Soldering condition 1.) Type of solder

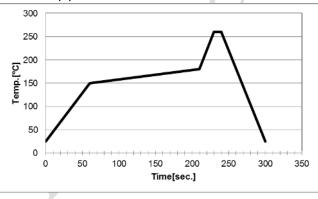
Material  $\rightarrow$  lead free solder paste Melting point  $\rightarrow$  +220±5°C

2.) Reflow temp.profile					
	Temp [°C]	Time[sec]			
Preheating	+150 to +180	150 (typ.)			
Peak	+260±5	10 (max.)			
Total	-	300 (max.)			

Frequency shift : ±2ppm

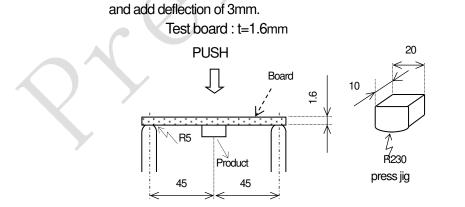
- 3.) Hand Soldering +350°C 3 sec max
- 4.) Reflow Times 2 times in below Reflow temp. profile

#### Reflow temp.profile



#### 8.8 Bending Strength

Solder this product in center of the circuit board (40mm X 100mm),



UNIT : mm

#### 9. Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

#### (2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.

#### (3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 3 times the ESR (Equivalent Series Resistance) of crystal unit.

#### 10. Storage conditions

Please store product in below conditions, and use within 6 months. Temperature +18 to +30°C, and Humidity of 20 to 70 % in the packaging condition.

#### 11. Manufacturing location

KYOCERA Corporation Shiga Yohkaichi Plant KYOCERA Corporation Yamagata Higashine Plant KYOCERA Crystal Device Corporation (THAILAND)

#### 12. Quality Assurance

Location

KYOCERA Corporation Yamagata Higashine Plant: Quality Assurance Division KYOCERA Corporation Shiga Yohkaichi Plant: Quality Assurance Division

#### 13. Quality guarantee

In the case when KYOCERA Corporation rooted failure occurred within 1 year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1 year of its delivery is waivered.

#### 14. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.